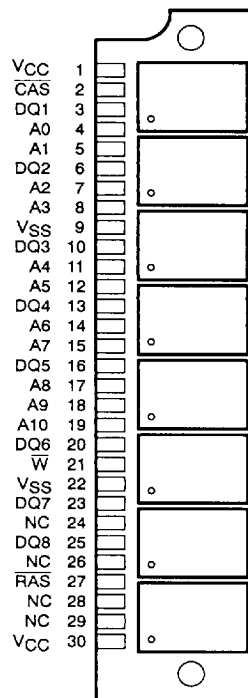


- Organization . . . 4 194 304 × 8
- Single 5-V Power Supply (±10% Tolerance)
- 30-Pin Single In-Line Memory Module (SIMM) for Use With Sockets
- Utilizes Eight 4-Megabit Dynamic RAMs in Plastic Small-Outline J-Lead Packages (SOJs)
- Long Refresh Period . . . 16 ms (1024 Cycles)
- All Inputs, Outputs, Clocks Fully TTL Compatible
- 3-State Output
- Performance Ranges:

	ACCESS TIME t _{RAC}	ACCESS TIME t _{AA}	ACCESS TIME t _{CAC}	READ OR WRITE CYCLE (MIN)
	(MAX)	(MAX)	(MAX)	(MIN)
'4100GAD8-60	60 ns	30 ns	15 ns	110 ns
'4100GAD8-70	70 ns	35 ns	18 ns	130 ns
'4100GAD8-80	80 ns	40 ns	20 ns	150 ns

- Common $\overline{\text{CAS}}$ Control for Eight Common Data-In and Data-Out Lines
- Low Power Dissipation
- Operating Free-Air Temperature Range 0°C to 70°C

SINGLE IN-LINE MODULE†
(TOP VIEW)

† The package shown is for pinout reference only.

description

The TM4100GAD8 is a dynamic random-access memory module organized as 4 194 304 × 8-bits in a 30-pin leadless single in-line memory module (SIMM).

The SIMM is composed of eight TMS44100DJ, 4 194 304 × 1-bit dynamic RAMs in 20/26-lead plastic small-outline J-lead packages (SOJ), mounted on a substrate with decoupling capacitors.

The TM4100GAD8 is available in the AD single-sided, leadless module for use with sockets.

The TM4100GAD8 is characterized for operation from 0°C to 70°C.

PIN NOMENCLATURE

A0–A10	Address Inputs
$\overline{\text{CAS}}$	Column-Address Strobe
DQ1–DQ8	Data In/Data Out
NC	No Internal Connection
$\overline{\text{RAS}}$	Row-Address Strobe
VCC	5-V Supply
VSS	Ground
W	Write Enable

PRODUCTION DATA: Information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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5-75

TM4100GAD8

62E D ■ 8961725 0080534 826 ■ TII5

4 194 304 BY 8-BIT DYNAMIC RAM MODULE

TEXAS INSTR (ASIC/MEMORY)

SMMS508A—MARCH 1992—REVISED JANUARY 1993

operation

The TM4100GAD8 operates as eight TMS44100DJs connected as shown in the functional block diagram. Refer to the TMS44100 data sheet for details of its operation. The common I/O feature of the TM4100GAD8 dictates the use of early write cycles to prevent contention on D and Q.

single in-line memory module and components

PC substrate: 1,27 mm (0.05 inch) nominal thickness; 0.005 inch/inch maximum warpage

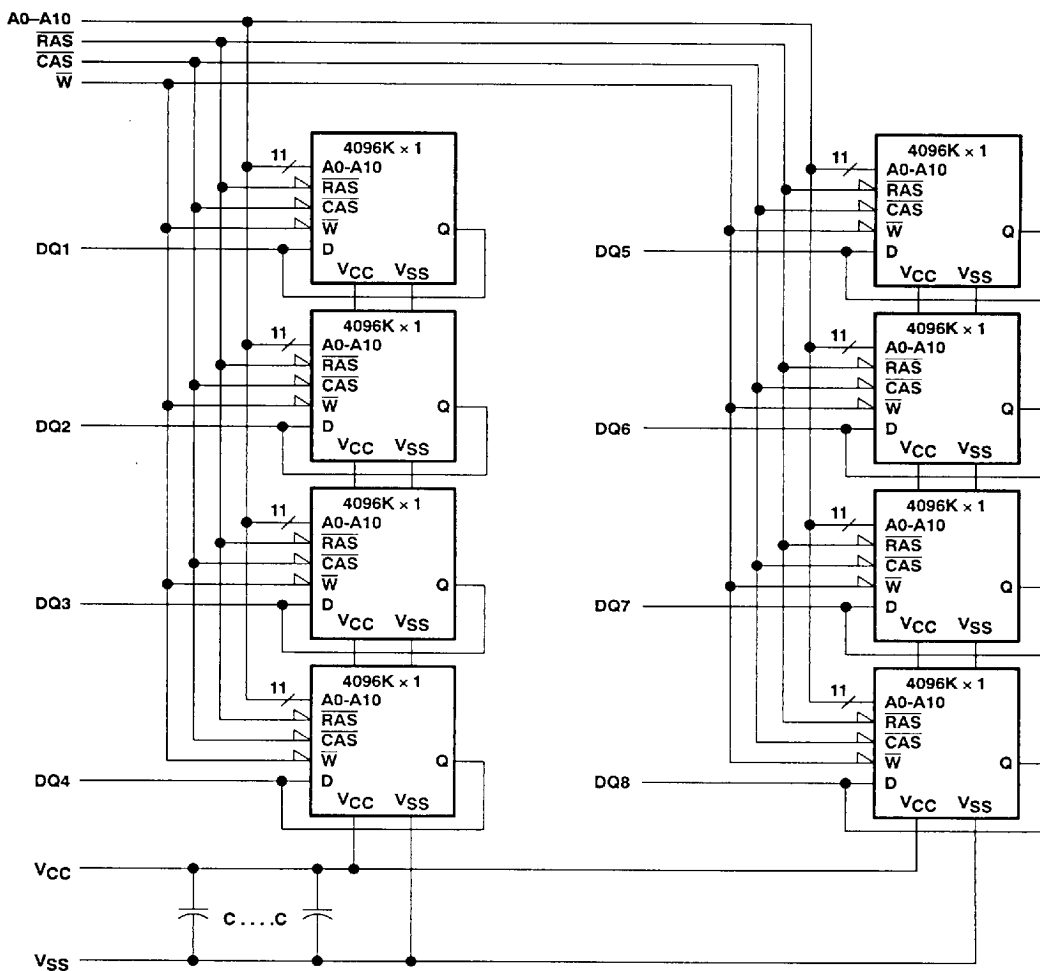
Bypass capacitors: Multilayer ceramic

Contact area for socketable devices: Nickel plate and solder plate over copper

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functional block diagram



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5-77

TM4100GAD8 62E D 8961725 0080536 6T9 TI15
4 194 304 BY 8-BIT DYNAMIC RAM MODULE

SMMS508A—MARCH 1992—REVISED JANUARY 1993

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range on any pin (see Note 1)	–1 V to 7 V
Supply voltage range on V _{CC}	–1 V to 7 V
Short circuit output current	50 mA
Power dissipation	8 W
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range	–55°C to 125°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the "recommended operating conditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to V_{SS}.

recommended operating conditions

	MIN	NOM	MAX	UNIT
V _{CC} Supply voltage	4.5	5	5.5	V
V _{IH} High-level input voltage	2.4		6.5	V
V _{IL} Low-level input voltage (see Note 2)	–1		0.8	V
T _A Operating free-air temperature	0		70	°C

NOTE 2: The algebraic convention, where the more negative (less positive) limit is designated as minimum, is used in this data sheet for logic voltage levels only.

electrical characteristics over full ranges of recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS	'4100GAD8-60		'4100GAD8-70		'4100GAD8-80		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
V _{OH} High-level output voltage	I _{OH} = –5 mA	2.4		2.4		2.4		V
V _{OL} Low-level output voltage	I _{OL} = 4.2 mA		0.4		0.4		0.4	V
I _I Input current (leakage)	V _{CC} = 5.5 V, V _I = 0 to 6.5 V, All other pins = 0 V to V _{CC}		±10		±10		±10	μA
I _O Output current (leakage)	V _O = 0 to V _{CC} , V _{CC} = 5.5 V, $\overline{\text{CAS}}$ high		±10		±10		±10	μA
I _{CC1} Read or write cycle current (see Note 3)	V _{CC} = 5.5 V, Minimum cycle		840		720		640	mA
I _{CC2} Standby current	V _{IH} = 2.4 V (TTL), After 1 memory cycle, $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ high,		16		16		16	mA
	V _{IH} = V _{CC} – 0.2 V (CMOS), After 1 memory cycle, $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ high		8		8		8	mA
I _{CC3} Average refresh current (RAS-only or CBR) (see Note 3)	V _{CC} = 5.5 V, Minimum cycle, $\overline{\text{RAS}}$ cycling, $\overline{\text{CAS}}$ high		840		720		640	mA
I _{CC4} Average page current (see Note 4)	V _{CC} = 5.5 V, t _{C(P)} = minimum, $\overline{\text{RAS}}$ low, $\overline{\text{CAS}}$ cycling		720		640		560	mA

NOTES: 3. Measured with a maximum of one address change while $\overline{\text{RAS}}$ = V_{IL}.
4. Measured with a maximum of one address change while $\overline{\text{CAS}}$ = V_{IH}.

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SMMS508A—MARCH 1992—REVISED JANUARY 1993

capacitance over recommended ranges of supply voltage and operating free-air temperature,
 $f = 1 \text{ MHz}$

PARAMETER		MIN	MAX	UNIT
$C_{i(A)}$	Input capacitance, address inputs		40	pF
$C_{i(RC)}$	Input capacitance, strobe inputs		56	pF
$C_{i(W)}$	Input capacitance, write-enable input		56	pF
C_o	Output capacitance (pins DQ1–DQ8)		12	pF

NOTE 5: V_{CC} equal to $5 \text{ V} \pm 0.5 \text{ V}$ and the bias on the pin under test is 0 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature

PARAMETER		'4100GAD8-60		'4100GAD8-70		'4100GAD8-80		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_{AA}	Access time from column-address		30		35		40	ns
t_{CAC}	Access time from $\overline{CAS}$ low		15		18		20	ns
t_{CPA}	Access time from column precharge		35		40		45	ns
t_{RAC}	Access time from $\overline{RAS}$ low		60		70		80	ns
t_{CLZ}	$\overline{CAS}$ to output in low Z	0		0		0		ns
t_{OFF}	Output disable time after $\overline{CAS}$ high (see Note 6)	0	15	0	18	0	20	ns

NOTE 6: t_{OFF} is specified when the output is no longer driven.

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5-79

TM4100GAD8
4 194 304 BY 8-BIT DYNAMIC RAM MODULE

62E D ■ 8961725 0080538 471 ■ TII5

SMMS508A—MARCH 1992—REVISED JANUARY 1993

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timing requirements over recommended ranges of supply voltage and operating free-air temperature

	'4100GAD8-60		'4100GAD8-70		'4100GAD8-80		UNIT
	MIN	MAX	MIN	MAX	MIN	MAX	
t _{RC} Random read or write cycle (see Note 7)	110		130		150		ns
t _{PC} Page-mode read or write cycle time (see Note 8)	40		45		50		ns
t _{RASP} Page-mode pulse duration, $\overline{\text{RAS}}$ low	60	100 000	70	100 000	80	100 000	ns
t _{RAS} Non-page-mode pulse duration, $\overline{\text{RAS}}$ low	60	10 000	70	10 000	80	10 000	ns
t _{CAS} Pulse duration, $\overline{\text{CAS}}$ low	15	10 000	18	10 000	20	10 000	ns
t _{CP} Pulse duration, $\overline{\text{CAS}}$ high	10		10		10		ns
t _{RP} Pulse duration, $\overline{\text{RAS}}$ high (precharge)	40		50		60		ns
t _{WP} Write pulse duration	15		15		15		ns
t _{ASC} Column-address setup time before $\overline{\text{CAS}}$ low	0		0		0		ns
t _{ASR} Row-address setup time before $\overline{\text{RAS}}$ low	0		0		0		ns
t _{DS} Data setup time	0		0		0		ns
t _{RCS} Read setup time before $\overline{\text{CAS}}$ low	0		0		0		ns
t _{CWL} $\overline{\text{W}}$ low setup time before $\overline{\text{CAS}}$ high	15		18		20		ns
t _{RWL} $\overline{\text{W}}$ low setup time before $\overline{\text{RAS}}$ high	15		18		20		ns
t _{WCS} $\overline{\text{W}}$ low setup time before $\overline{\text{CAS}}$ low	0		0		0		ns
t _{WSR} $\overline{\text{W}}$ high setup time ($\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh only)	10		10		10		ns
t _{WTS} $\overline{\text{W}}$ low setup time (test mode only)	10		10		10		ns
t _{CAH} Column-address hold time after $\overline{\text{CAS}}$ low	10		15		15		ns
t _{DHR} Data hold time after $\overline{\text{RAS}}$ low (see Note 9)	50		55		60		ns
t _{DH} Data hold time	10		15		15		ns
t _{AR} Column-address hold time after $\overline{\text{RAS}}$ low (see Note 9)	50		55		60		ns
t _{RAH} Row-address hold time after $\overline{\text{RAS}}$ low	10		10		10		ns
t _{RCH} Read hold time after $\overline{\text{CAS}}$ high (see Note 10)	0		0		0		ns
t _{RRH} Read hold time after $\overline{\text{RAS}}$ high (see Note 10)	0		0		0		ns
t _{WCH} Write hold time after $\overline{\text{CAS}}$ low	15		15		15		ns
t _{WCR} Write hold time after $\overline{\text{RAS}}$ low (see Note 9)	50		55		60		ns
t _{WHR} $\overline{\text{W}}$ high hold time ($\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh only)	10		10		10		ns
t _{WTH} $\overline{\text{W}}$ low hold time (test mode only)	10		10		10		ns

Continued next page.

- NOTES: 7. All cycle times assume $t_T = 5$ ns.
8. To assure t_{PC} min, t_{ASC} should be greater than or equal to t_{CP} .
9. The minimum value is measured when t_{RCD} is set to t_{RCD} min as a reference.
10. Either t_{RRH} or t_{RCH} must be satisfied for a read cycle.

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SMMS508A-MARCH 1992-REVISED JANUARY 1993

timing requirements over recommended ranges of supply voltage and operating free-air temperature (concluded)

		'4100GAD8-60		'4100GAD8-70		'4100GAD8-80		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _{CHR}	Delay time, $\overline{\text{RAS}}$ low to $\overline{\text{CAS}}$ high (CAS-before-RAS refresh only)	15		15		20		ns
t _{CRP}	Delay time, $\overline{\text{CAS}}$ high to $\overline{\text{RAS}}$ low	0		0		0		ns
t _{CSH}	Delay time, $\overline{\text{RAS}}$ low to $\overline{\text{CAS}}$ high	60		70		80		ns
t _{CSR}	Delay time, $\overline{\text{CAS}}$ low to $\overline{\text{RAS}}$ low (CAS-before-RAS refresh only)	10		10		10		ns
t _{RAD}	Delay time, $\overline{\text{RAS}}$ low to column-address (see Note 11)	15	30	15	35	15	40	ns
t _{RAL}	Delay time, column-address to $\overline{\text{RAS}}$ high	30		35		40		ns
t _{CAL}	Delay time, column-address to $\overline{\text{CAS}}$ high	30		35		40		ns
t _{RCD}	Delay time, $\overline{\text{RAS}}$ low to $\overline{\text{CAS}}$ low (see Note 11)	20	45	20	52	20	60	ns
t _{RPC}	Delay time, $\overline{\text{RAS}}$ high to $\overline{\text{CAS}}$ low	0		0		0		ns
t _{RSH}	Delay time, $\overline{\text{CAS}}$ low to $\overline{\text{RAS}}$ high	15		18		20		ns
t _{TAA}	Access time from address (test mode)	35		40		45		ns
t _{TCPA}	Access time from column precharge (test mode)	40		45		50		ns
t _{TRAC}	Access time from $\overline{\text{RAS}}$ (test mode)	65		75		85		ns
t _{REF}	Refresh time interval		16		16		16	ms
t _T	Transition time	2	50	2	50	2	50	ns

NOTE 11: The maximum value is specified only to assure access time.



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5-81

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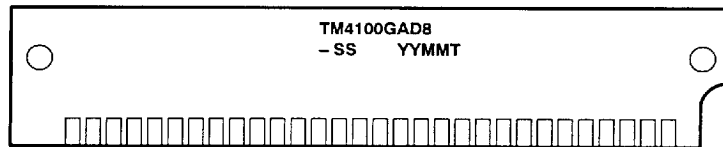
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4 194 304 BY 8-BIT DYNAMIC RAM MODULE

SMMS508A-MARCH 1992-REVISED JANUARY 1993

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device symbolization



YY = Year Code
MM = Month Code
T = Assembly Site Code
-SS = Speed

NOTE: The location of symbolization may vary.